
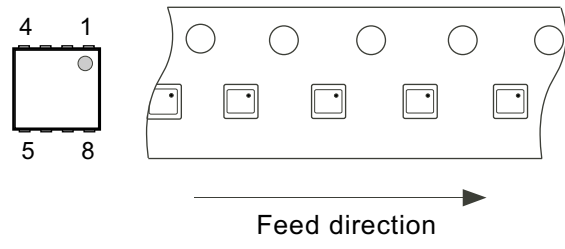
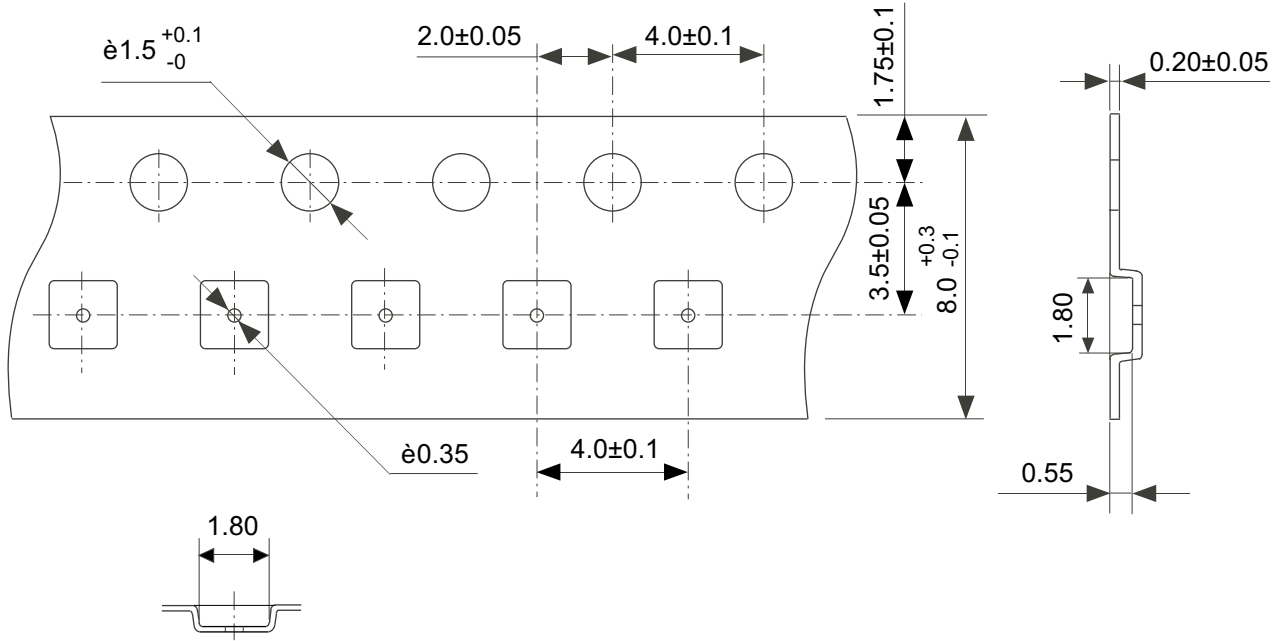


※ The heat sink of back side has different electric potential depending on the product. Confirm specifications of each product. Do not use it as the function of electrode.

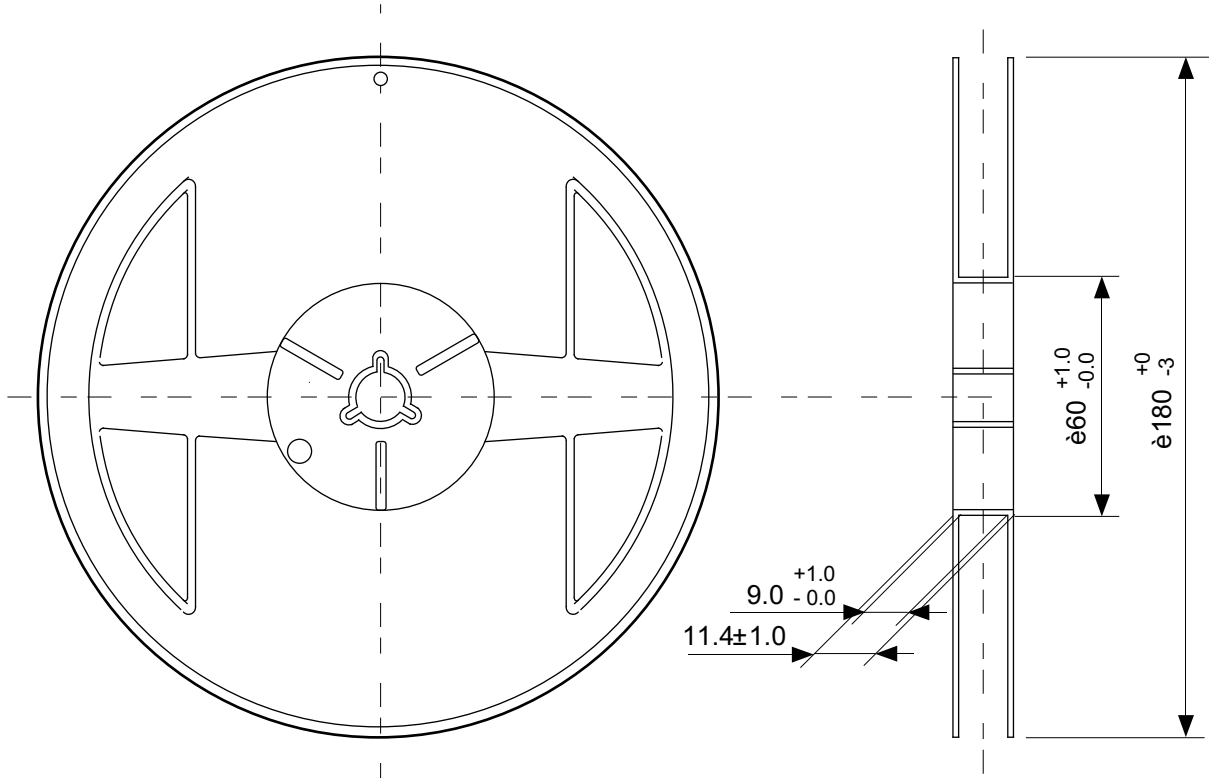
No. PY008-B-P-SD-1.0

TITLE	HSNT-8-C-PKG Dimensions
No.	PY008-B-P-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

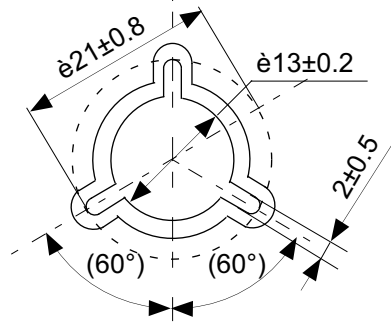


No. PY008-B-C-SD-1.0

TITLE	HSNT-8-C-Carrier Tape
No.	PY008-B-C-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	

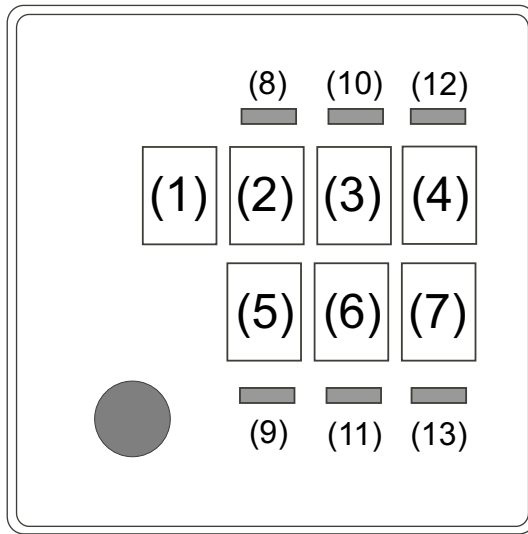


Enlarged drawing in the central part



No. PY008-B-R-SD-1.0

TITLE	HSNT-8-C-Reel		
No.	PY008-B-R-SD-1.0		
ANGLE		QTY.	5,000
UNIT	mm		
ABLIC Inc.			



(1) to (4) : Product code

(5) to (7) : Lot No.

(8) , (9) : Year of assembly (bar)

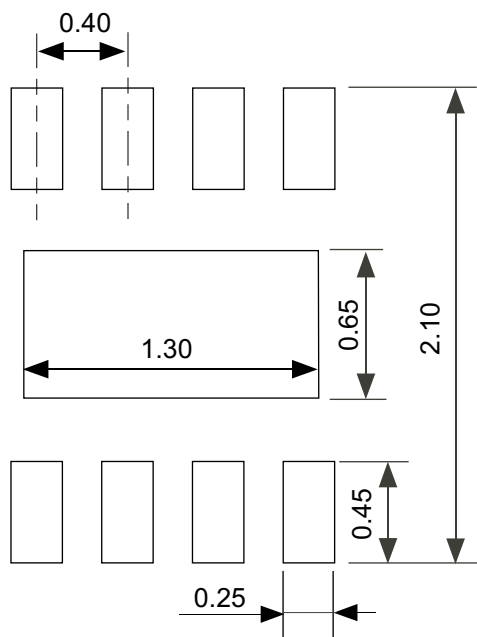
(10) to (13) : Month of assembly (bar)

● : 1Pin mark

No. PY008-B-M-SD-1.0

TITLE	HSNT-8-C-Markings		
No.	PY008-B-M-SD-1.0		
ANGLE			
UNIT		TYPE	LASER
ABLIC Inc.			

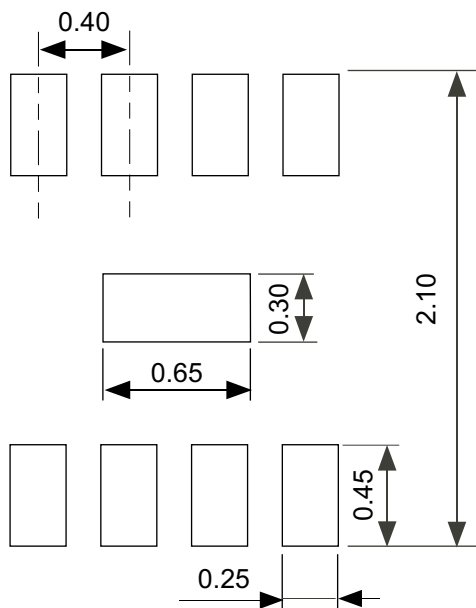
Land Pattern



Caution It is recommended to solder the heat sink to a board in order to ensure the heat radiation.

注意 放熱性を確保する為に、PKGの裏面放熱板(ヒートシンク)を基板に半田付けする事を推奨いたします。

Metal Mask Pattern



Caution

- ① Mask aperture ratio of the lead mounting part is 100%.
- ② Mask aperture ratio of the heat sink mounting part is 20%.
- ③ Mask thickness: t0.10 mm

注意

- ① リード実装部のマスク開口率は100%です。
- ② 放熱板実装のマスク開口率は20%です。
- ③ マスク厚み : t0.10 mm

No. PY008-B-L-SD-1.0

TITLE	HSNT-8-C -Land Recommendation
No.	PY008-B-L-SD-1.0
ANGLE	
UNIT	mm
ABLIC Inc.	